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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	ARM7TDMI
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	90MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	Keypad, LCD, Touchscreen
Ethernet	-
SATA	-
USB	-
Voltage - I/O	2.5V, 2.7V, 3.0V, 3.3V
Operating Temperature	-40°C ~ 85°C (TA)
Security Features	Hardware ID
Package / Case	204-TFBGA
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/cirrus-logic/ep7311-ir-90

CODEC Interface

The EP7311 includes an interface to telephony-type CODECs for easy integration into voice-over-IP and other voice communications systems. The CODEC interface is multiplexed to the same pins as the MCP and SSI2.

Pin Mnemonic	I/O	Pin Description
PCMCLK	O	Serial bit clock
PCMOUT	O	Serial data out
PCMIN	I	Serial data in
PCMSYNC	O	Frame sync

Table F. CODEC Interface Pin Assignments

Note: See Table R on page 11 for information on pin multiplexes.

SSI2 Interface

An additional SPI/Microwire1-compatible interface is available for both master and slave mode communications. The SSI2 unit shares the same pins as the MCP and CODEC interfaces through a multiplexer.

- Synchronous clock speeds of up to 512 kHz
- Separate 16 entry TX and RX half-word wide FIFOs
- Half empty/full interrupts for FIFOs
- Separate RX and TX frame sync signals for asymmetric traffic

Pin Mnemonic	I/O	Pin Description
SSICLK	I/O	Serial bit clock
SSITXDA	O	Serial data out
SSIRXDA	I	Serial data in
SSITXFR	I/O	Transmit frame sync
SSIRXFR	I/O	Receive frame sync

Table G. SSI2 Interface Pin Assignments

Note: See Table R on page 11 for information on pin multiplexes.

Synchronous Serial Interface

- ADC (SSI) Interface: Master mode only; SPI and Microwire1-compatible (128 kbps operation)
- Selectable serial clock polarity

Pin Mnemonic	I/O	Pin Description
ADCLK	O	SSI1 ADC serial clock
ADCIN	I	SSI1 ADC serial input
ADCOUT	O	SSI1 ADC serial output
nADCCS	O	SSI1 ADC chip select
SMPCLK	O	SSI1 ADC sample clock

Table H. Serial Interface Pin Assignments

LCD Controller

A DMA address generator is provided that fetches video display data for the LCD controller from memory. The display frame buffer start address is programmable, allowing the LCD frame buffer to be in SDRAM, internal SRAM or external SRAM.

- Interfaces directly to a single-scan panel monochrome STN LCD
- Interfaces to a single-scan panel color STN LCD with minimal external glue logic
- Panel width size is programmable from 32 to 1024 pixels in 16-pixel increments
- Video frame buffer size programmable up to 128 KB
- Bits per pixel of 1, 2, or 4 bits

Pin Mnemonic	I/O	Pin Description
CL1	O	LCD line clock
CL2	O	LCD pixel clock out
DD[3:0]	O	LCD serial display data bus
FRM	O	LCD frame synchronization pulse
M	O	LCD AC bias drive

Table I. LCD Interface Pin Assignments

64-Keypad Interface

Matrix keyboards and keypads can be easily read by the EP7311. A dedicated 8-bit column driver output generates strobes for each keyboard column signal. The pins of Port A, when configured as inputs, can be selectively OR'ed together to provide a keyboard interrupt that is capable of waking the system from a STANDBY or IDLE state.

- Column outputs can be individually set high with the remaining bits left at high-impedance
- Column outputs can be driven all-low, all-high, or all-high-impedance
- Keyboard interrupt driven by OR'ing together all Port A bits
- Keyboard interrupt can be used to wake up the system
- 8×8 keyboard matrix usable with no external logic, extra keys can be added with minimal glue logic

Pin Mnemonic	I/O	Pin Description
COL[7:0]	O	Keyboard scanner column drive

Table J. Keypad Interface Pin Assignments

Interrupt Controller

When unexpected events arise during the execution of a program (i.e., interrupt or memory fault) an exception is usually generated. When these exceptions occur at the same time, a fixed priority system determines the order in which they are handled. The EP7311 interrupt controller has two interrupt types: interrupt request (IRQ) and fast interrupt request (FIQ). The interrupt controller has the ability to control interrupts from 22 different FIQ and IRQ sources.

- Supports 22 interrupts from a variety of sources (such as UARTs, SSI1, and key matrix.)
- Routes interrupt sources to the ARM720T's IRQ or FIQ (Fast IRQ) inputs
- Five dedicated off-chip interrupt lines operate as level sensitive interrupts

.

Pin Mnemonic	I/O	Pin Description
nEINT[2:1]	I	External interrupt
EINT[3]	I	External interrupt
nEXTFIQ	I	External Fast Interrupt input
nMEDCHG/nBROM (Note)	I	Media change interrupt input

Table K. Interrupt Controller Pin Assignments

Note: Pins are multiplexed. See Table S on page 11 for more information.

Real-Time Clock

The EP7311 contains a 32-bit Real Time Clock (RTC) that can be written to and read from in the same manner as the timer counters. It also contains a 32-bit output match register which can be programmed to generate an interrupt.

- Driven by an external 32.768 kHz crystal oscillator

Pin Mnemonic	Pin Description
RTCIN	Real-Time Clock Oscillator Input
RTCOUT	Real-Time Clock Oscillator Output
VDDRTC	Real-Time Clock Oscillator Power
VSSRTC	Real-Time Clock Oscillator Ground

Table L. Real-Time Clock Pin Assignments

PLL and Clocking

- Processor and Peripheral Clocks operate from a single 3.6864 MHz crystal or external 13 MHz clock
- Programmable clock speeds allow the peripheral bus to run at 18 MHz when the processor is set to 18 MHz and at 36 MHz when the processor is set to 36, 49 or 74 MHz

Pin Mnemonic	Pin Description
MOSCIN	Main Oscillator Input
MOSCOUT	Main Oscillator Output
VDDOSC	Main Oscillator Power
VSSOSC	Main Oscillator Ground

Table M. PLL and Clocking Pin Assignments

ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings

DC Core, PLL, and RTC Supply Voltage	2.9 V
DC I/O Supply Voltage (Pad Ring)	3.6 V
DC Pad Input Current	±10 mA/pin; ±100 mA cumulative
Storage Temperature, No Power	–40°C to +125°C

Recommended Operating Conditions

DC core, PLL, and RTC Supply Voltage	2.5 V ± 0.2 V
DC I/O Supply Voltage (Pad Ring)	2.3 V - 3.5 V
DC Input / Output Voltage	O–I/O supply voltage
Operating Temperature	Extended -20°C to +70°C; Commercial 0°C to +70°C; Industrial -40°C to +85°C

DC Characteristics

All characteristics are specified at V_{DDCORE} = 2.5 V, V_{DDIO} = 3.3 V and V_{SS} = 0 V over an operating temperature of 0°C to +70°C for all frequencies of operation. The current consumption figures have test conditions specified per parameter."

Symbol	Parameter	Min	Typ	Max	Unit	Conditions
VIH	CMOS input high voltage	$0.65 \times V_{DDIO}$	-	V_{DDIO} + 0.3	V	V_{DDIO} = 2.5 V
VIL	CMOS input low voltage	V_{SS} – 0.3	-	$0.25 \times V_{DDIO}$	V	V_{DDIO} = 2.5 V
VT+	Schmitt trigger positive going threshold	-	-	2.1	V	
VT-	Schmitt trigger negative going threshold	0.8	-	-	V	
Vhst	Schmitt trigger hysteresis	0.1	-	0.4	V	VIL to VIH
VOH	CMOS output high voltage[a] Output drive 1[a] Output drive 2[a]	V_{DD} – 0.2 2.5 2.5	- - -	- - -	V V V	IOH = 0.1 mA IOH = 4 mA IOH = 12 mA
VOL	CMOS output low voltage[a] Output drive 1[a] Output drive 2[a]	- - -	- - -	0.3 0.5 0.5	V V V	IOL = –0.1 mA IOL = –4 mA IOL = –12 mA
IIN	Input leakage current	-	-	1.0	µA	VIN = V_{DD} or GND
IOZ	Bidirectional 3-state leakage current[b c]	25	-	100	µA	VOUT = V_{DD} or GND
CIN	Input capacitance	8	-	10.0	pF	
COUT	Output capacitance	8	-	10.0	pF	

SDRAM Interface

Figure 3 through Figure 6 define the timings associated with all phases of the SDRAM. The following table contains the values for the timings of each of the SDRAM modes.

Parameter	Symbol	Min	Typ	Max	Unit
SDCLK rising edge to SDCS assert delay time	t_{CSa}	0	2	4	ns
SDCLK rising edge to SDCS deassert delay time	t_{CSd}	– 3	2	10	ns
SDCLK rising edge to SDRAS assert delay time	t_{RAa}	1	3	7	ns
SDCLK rising edge to SDRAS deassert delay time	t_{RAd}	– 3	1	10	ns
SDCLK rising edge to SDRAS invalid delay time	t_{RAnv}	2	4	7	ns
SDCLK rising edge to SDCAS assert delay time	t_{CAa}	– 2	2	5	ns
SDCLK rising edge to SDCAS deassert delay time	t_{CAd}	– 5	0	3	ns
SDCLK rising edge to ADDR transition time	t_{ADv}	– 3	1	5	ns
SDCLK rising edge to ADDR invalid delay time	t_{ADx}	– 2	2	5	ns
SDCLK rising edge to SDMWE assert delay time	t_{MWa}	– 3	1	5	ns
SDCLK rising edge to SDMWE deassert delay time	t_{MWd}	– 4	0	4	ns
DATA transition to SDCLK rising edge time	t_{DAs}	2	-	-	ns
SDCLK rising edge to DATA transition hold time	t_{DAh}	1	-	-	ns
SDCLK rising edge to DATA transition delay time	t_{DAd}	0	-	15	ns

Static Memory

Figure 7 through Figure 10 define the timings associated with all phases of the Static Memory. The following table contains the values for the timings of each of the Static Memory modes.

Parameter	Symbol	Min	Typ	Max	Unit
EXPCLK rising edge to nCS assert delay time	t_{CSd}	2	8	20	ns
EXPCLK falling edge to nCS deassert hold time	t_{CSh}	2	7	20	ns
EXPCLK rising edge to A assert delay time	t_{Ad}	4	9	16	ns
EXPCLK falling edge to A deassert hold time	t_{Ah}	3	10	19	ns
EXPCLK rising edge to nMWE assert delay time	t_{MWd}	3	6	10	ns
EXPCLK rising edge to nMWE deassert hold time	t_{MWh}	3	6	10	ns
EXPCLK falling edge to nMOE assert delay time	t_{MOEd}	3	7	10	ns
EXPCLK falling edge to nMOE deassert hold time	t_{MOEh}	2	7	10	ns
EXPCLK falling edge to HALFWORD deassert delay time	t_{HWd}	2	8	20	ns
EXPCLK falling edge to WORD assert delay time	t_{WDd}	2	8	16	ns
EXPCLK rising edge to data valid delay time	t_{Dv}	8	13	21	ns
EXPCLK falling edge to data invalid delay time	t_{Dnv}	6	15	30	ns
Data setup to EXPCLK falling edge time	t_{Ds}	-	-	1	ns
EXPCLK falling edge to data hold time	t_{Dh}	-	-	3	ns
EXPCLK rising edge to WRITE assert delay time	t_{WRd}	5	11	23	ns
EXPREADY setup to EXPCLK falling edge time	t_{EXs}	-	-	0	ns
EXPCLK falling edge to EXPREADY hold time	t_{EXh}	-	-	0	ns

Static Memory Single Write Cycle

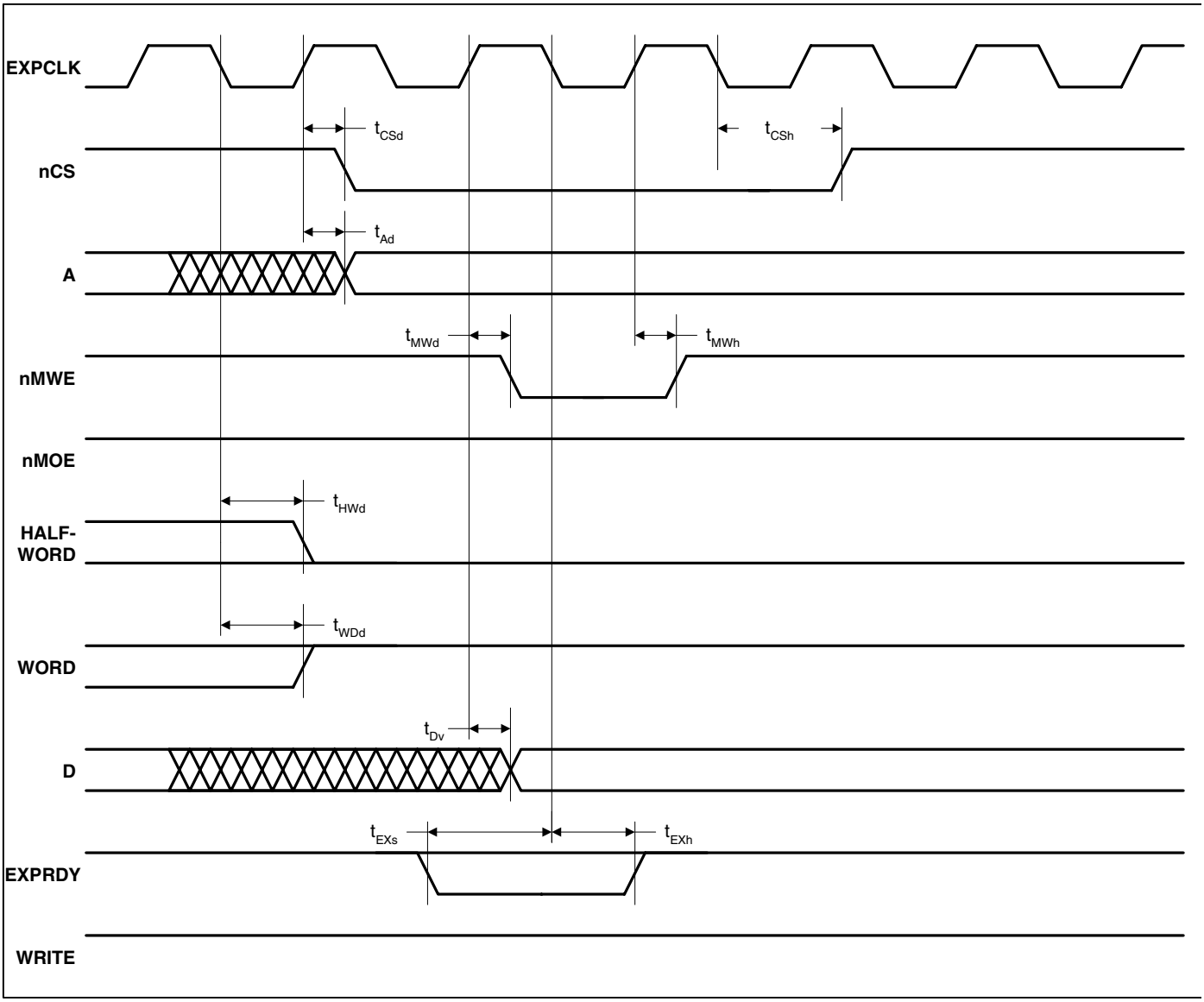

Figure 8. Static Memory Single Write Cycle Timing Measurement

Note: 1. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.

2. Zero wait states for sequential writes is not permitted for memory devices which use nMWE pin, as this cannot be driven with valid timing under zero wait state conditions.

3. Address, Data, Halfword, Word, and Write hold state until next cycle.

Static Memory Burst Write Cycle

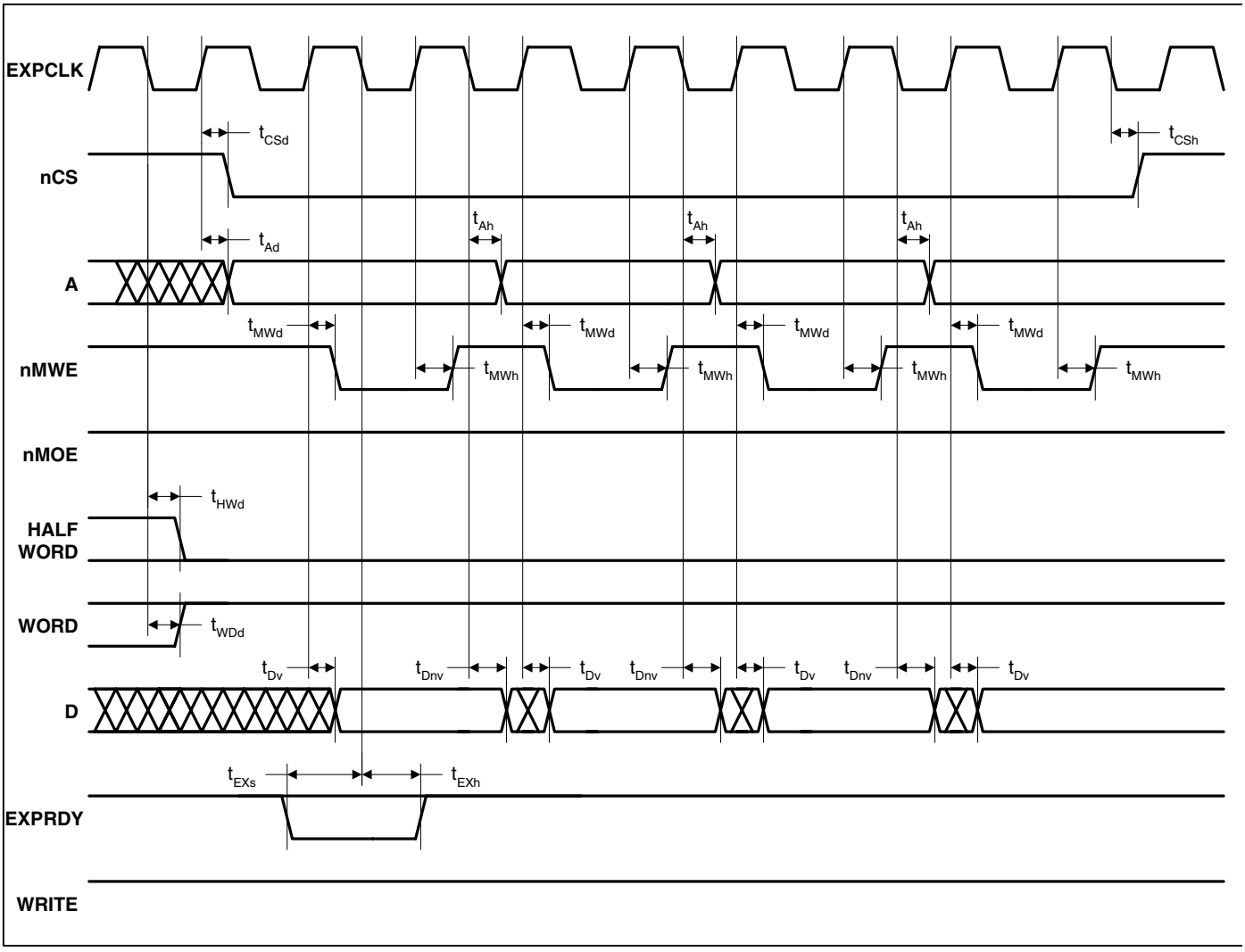

Figure 10. Static Memory Burst Write Cycle Timing Measurement

Note: 1. Four cycles are shown in the above diagram (minimum wait states, 1-1-1-1). This is the maximum number of consecutive cycles that can be driven. The number of consecutive cycles can be programmed from 2 to 4, inclusively.
2. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
3. Zero wait states for sequential writes is not permitted for memory devices which use nMWE pin, as this cannot be driven with valid timing under zero wait state conditions.
4. Address, Data, Halfword, Word, and Write hold state until next cycle.

SSI2 Interface

Parameter	Symbol	Min	Max	Unit
SSICLK period (slave mode)	t_{clk_per}	185	2050	ns
SSICLK high time	t_{clk_high}	925	1025	ns
SSICLK low time	t_{clk_low}	925	1025	ns
SSICLK rise/fall time	t_{clkrf}	3	18	ns
SSICLK rising edge to RX and/or TX frame sync high time	t_{FRd}	-	3	ns
SSICLK rising edge to RX and/or TX frame sync low time	t_{FRa}	-	8	ns
SSIRXFR and/or SSITXFR period	t_{FR_per}	960	990	ns
SSIRXDA setup to SSICLK falling edge time	t_{RXs}	3	7	ns
SSIRXDA hold from SSICLK falling edge time	t_{RXh}	3	7	ns
SSICLK rising edge to SSITXDA data valid delay time	t_{TXd}	-	2	ns
SSITXDA valid time	t_{TXv}	960	990	ns

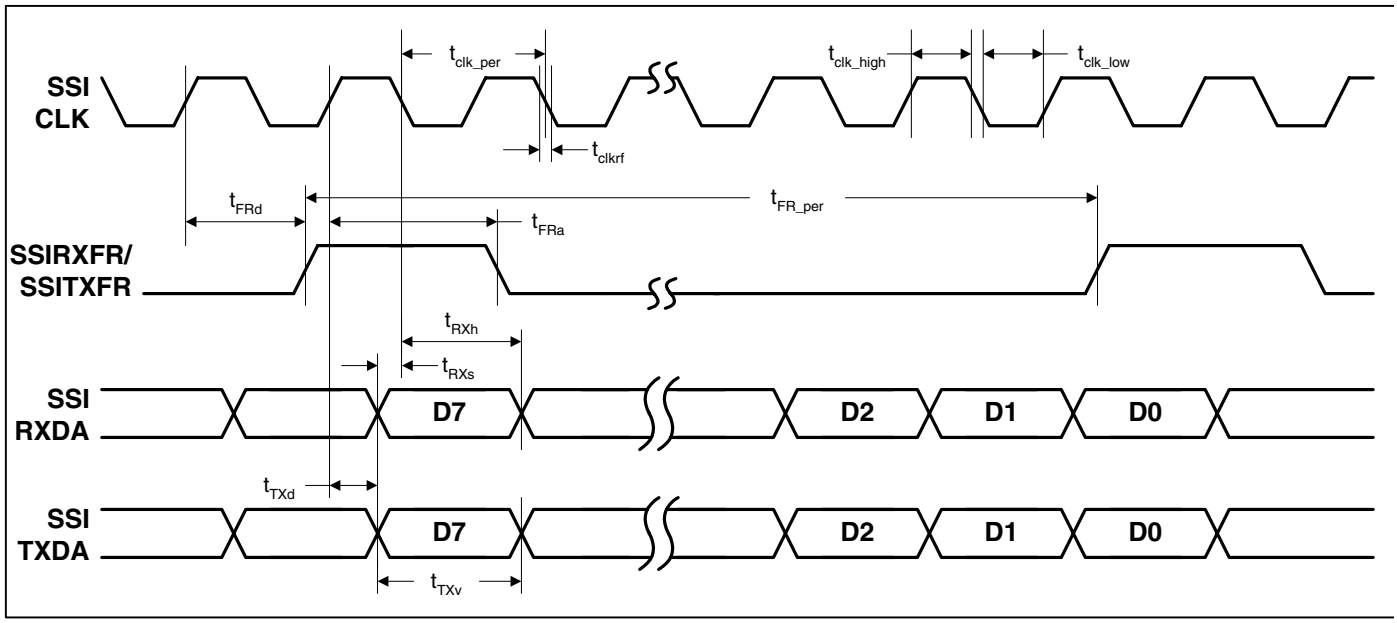

Figure 12. SSI2 Interface Timing Measurement

LCD Interface

Parameter	Symbol	Min	Max	Unit
CL[2] falling to CL[1] rising delay time	t_{CL1d}	– 10	25	ns
CL[1] falling to CL[2] rising delay time	t_{CL2d}	80	3,475	ns
CL[1] falling to FRM transition time	t_{FRMd}	300	10,425	ns
CL[1] falling to M transition time	t_{Md}	– 10	20	ns
CL[2] rising to DD (display data) transition time	t_{DDd}	– 10	20	ns

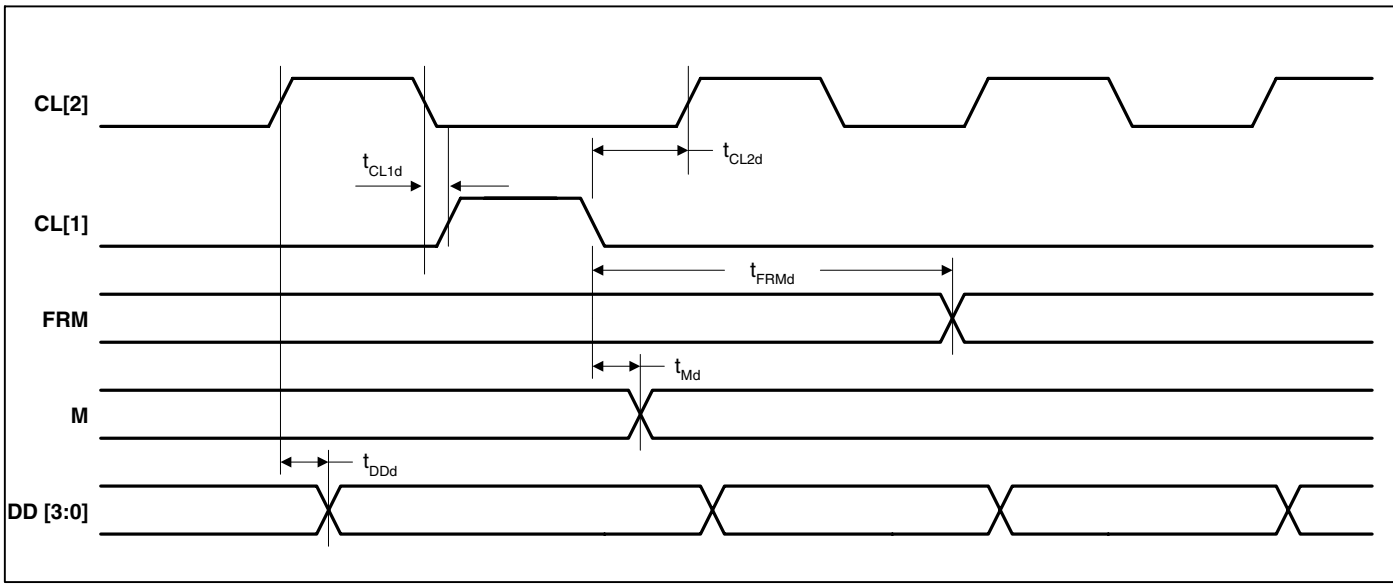

Figure 13. LCD Controller Timing Measurement

Table T. 208-Pin LQFP Numeric Pin Listing (Continued)

Pin No.	Signal	Type	Strength	Reset State
73	VSSIO	Pad Gnd		
74	VDDIO	Pad Pwr		
75	DRIVE[1]	I/O	2	High / Low
76	DRIVE[0]	I/O	2	High / Low
77	ADCCLK	O	1	Low
78	ADCOUT	O	1	Low
79	SMPCLK	O	1	Low
80	FB[1]	I		
81	VSSIO	Pad Gnd		
82	FB[0]	I		
83	COL[7]	O	1	High
84	COL[6]	O	1	High
85	COL[5]	O	1	High
86	COL[4]	O	1	High
87	COL[3]	O	1	High
88	COL[2]	O	1	High
89	VDDIO	Pad Pwr		
90	TCLK	I		
91	COL[1]	O	1	High
92	COL[0]	O	1	High
93	BUZ	O	1	Low
94	D[31]	I/O	1	Low
95	D[30]	I/O	1	Low
96	D[29]	I/O	1	Low
97	D[28]	I/O	1	Low
98	VSSIO	Pad Gnd		
99	A[27]/DRA[0]	O	2	Low
100	D[27]	I/O	1	Low
101	A[26]/DRA[1]	O	2	Low
102	D[26]	I/O	1	Low
103	A[25]/DRA[2]	O	2	Low
104	D[25]	I/O	1	Low
105	HALFWORD	O	1	Low
106	A[24]/DRA[3]	O	1	Low
107	VDDIO	Pad Pwr		—
108	VSSIO	Pad Gnd		—
109	D[24]	I/O	1	Low

Table T. 208-Pin LQFP Numeric Pin Listing (Continued)

Pin No.	Signal	Type	Strength	Reset State
110	A[23]/DRA[4]	O	1	Low
111	D[23]	I/O	1	Low
112	A[22]/DRA[5]	O	1	Low
113	D[22]	I/O	1	Low
114	A[21]/DRA[6]	O	1	Low
115	D[21]	I/O	1	Low
116	VSSIO	Pad Gnd		
117	A[20]/DRA[7]	O	1	Low
118	D[20]	I/O	1	Low
119	A[19]/DRA[8]	O	1	Low
120	D[19]	I/O	1	Low
121	A[18]/DRA[9]	O	1	Low
122	D[18]	I/O	1	Low
123	VDDIO	Pad Pwr		
124	VSSIO	Pad Gnd		
125	nTRST	I		
126	A[17]/DRA[10]	O	1	Low
127	D[17]	I/O	1	Low
128	A[16]/DRA[11]	O	1	Low
129	D[16]	I/O	1	Low
130	A[15]/DRA[12]	O	1	Low
131	D[15]	I/O	1	Low
132	A[14]/DRA[13]	O	1	Low
133	D[14]	I/O	1	Low
134	A[13]/DRA[14]	O	1	Low
135	D[13]	I/O	1	Low
136	A[12]	O	1	Low
137	D[12]	I/O	1	Low
138	A[11]	O	1	Low
139	VDDIO	Pad Pwr		
140	VSSIO	Pad Gnd		
141	D[11]	I/O	1	Low
142	A[10]	O	1	Low
143	D[10]	I/O	1	Low
144	A[9]	O	1	Low
145	D[9]	I/O	1	Low
146	A[8]	O	1	Low
147	D[8]	I/O	1	Low

Table T. 208-Pin LQFP Numeric Pin Listing (Continued)

Pin No.	Signal	Type	Strength	Reset State
148	A[7]	O	1	Low
149	VSSIO	Pad Gnd		
150	D[7]	I/O	1	Low
151	nBATCHG	I		
152	nEXTPWR	I		
153	BATOK	I		
154	nPOR	I	Schmitt	
155	nMEDCHG/ nBROM	I		
156	nURESET	I	Schmitt	
157	VDDOSC	Osc Pwr		
158	MOSCIN	Osc		
159	MOSCOUT	Osc		
160	VSSOSC	Osc Gnd		
161	WAKEUP	I	Schmitt	
162	nPWRFL	I		
163	A[6]	O	1	Low
164	D[6]	I/O	1	Low
165	A[5]	Out	1	Low
166	D[5]	I/O	1	Low
167	VDDIO	Pad Pwr		
168	VSSIO	Pad Gnd		
169	A[4]	O	1	Low
170	D[4]	I/O	1	Low
171	A[3]	O	2	Low
172	D[3]	I/O	1	Low
173	A[2]	O	2	Low
174	VSSIO	Pad Gnd		
175	D[2]	I/O	1	Low
176	A[1]	O	2	Low
177	D[1]	I/O	1	Low
178	A[0]	O	2	Low
179	D[0]	I/O	1	Low
180	VSS CORE	Core Gnd		
181	VDD CORE	Core Pwr		
182	VSSIO	Pad Gnd		
183	VDDIO	Pad Pwr		
184	CL[2]	O	1	Low
185	CL[1]	O	1	Low

Table T. 208-Pin LQFP Numeric Pin Listing (Continued)

Pin No.	Signal	Type	Strength	Reset State
186	FRM	O	1	Low
187	M	O	1	Low
188	DD[3]	I/O	1	Low
189	DD[2]	I/O	1	Low
190	VSSIO	Pad Gnd		
191	DD[1]	I/O	1	Low
192	DD[0]	I/O	1	Low
193	nSDCS[1]	O	1	High
194	nSDCS[0]	O	1	High
195	SDQM[3]	I/O	2	Low
196	SDQM[2]	I/O	2	Low
197	VDDIO	Pad Pwr		
198	VSSIO	Pad Gnd		
199	SDCKE	I/O	2	Low
200	SDCLK	I/O	2	Low
201	nMWE/nSDWE	O	1	High
202	nMOE/nSDCAS	O	1	High
203	VSSIO	Pad Gnd		
204	nCS[0]	O	1	High
205	nCS[1]	O	1	High
206	nCS[2]	O	1	High
207	nCS[3]	O	1	High
208	nCS[4]	O	1	High

*With p/u' means with internal pull-up on the pin.

204-Ball TFBGA Package Characteristics

204-Ball TFBGA Package Specifications

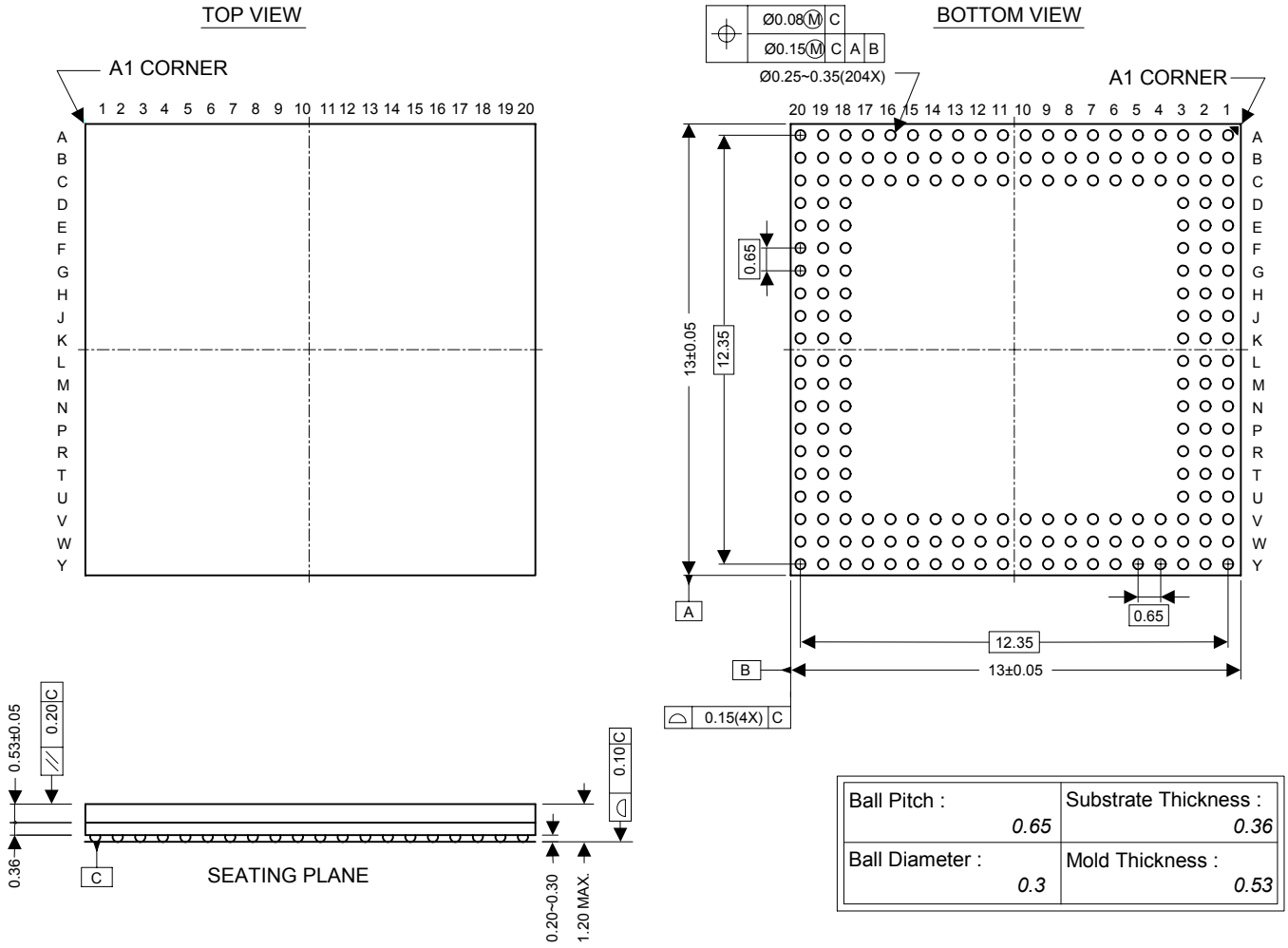

Figure 17. 204-Ball TFBGA Package

204-Ball TFBGA Ball Listing

The list is ordered by ball location.

Table 21. 204-Ball TFBGA Ball Listing

Ball Location	Name	Strength†	Reset State	Type	Description
A1	VDDIO			Pad power	Digital I/O power, 3.3 V
A2	EXPCLK	1		I	Expansion clock input
A3	nCS[3]	1	High	O	Chip select 3
A4	nCS[1]	1	High	O	Chip select 1
A5	nMWE/nSDWE	1	High	O	ROM, expansion write enable/ SDRAM write enable control signal
A6	SDQM[2]	2	Low	O	SDRAM byte lane mask
A7	nSDCS[1]	1	High	O	SDRAM chip select 2
A8	DD[2]	1	Low	O	LCD serial display data
A9	FRM	1	Low	O	LCD frame synchronization pulse
A10	CL[1]	1	Low	O	LCD line clock
A11	VSSCORE			Core ground	Core ground
A12	D[1]	1	Low	I/O	Data I/O
A13	A[2]	2	Low	O	System byte address
A14	D[4]	1	Low	I/O	Data I/O
A15	A[5]	1	Low	O	System byte address
A16	nPWRFL			I	Power fail sense input
A17	MOSCOUT			O	Main oscillator out
A18	VSSIO			Pad ground	I/O ground
A19	VSSIO			Pad ground	I/O ground
A20	VSSIO			Pad ground	I/O ground
B1	WORD	1	Low	O	Word access select output
B2	VDDIO			Pad power	Digital I/O power, 3.3 V
B3	nCS[5]	1	Low	O	Chip select 5
B4	nCS[2]	1	High	O	Chip select 2
B5	nMOE/nSDCAS	1	High	O	ROM, expansion OP enable/SDRAM CAS control signal
B6	SDCKE	2	Low	O	SDRAM clock enable output
B7	nSDCS[0]	1	High	O	SDRAM chip select 0

Table 21. 204-Ball TFBGA Ball Listing (Continued)

Ball Location	Name	Strength†	Reset State	Type	Description
H19	D[12]	1	Low	I/O	Data I/O
H20	A[12]	1	Low	O	System byte address
J1	PA[4]	1	Input‡	I/O	GPIO port A
J2	PA[5]	1	Input‡	I/O	GPIO port A
J3	PA[6]	1	Input‡	I/O	GPIO port A
J18	A[11]	1	Low	O	System byte address
J19	D[13]	1	Low	I/O	Data I/O
J20	A[13]/DRA[14]	1	Low	O	System byte address / SDRAM address
K1	PA[1]	1	Input‡	I/O	GPIO port A
K2	PA[2]	1	Input‡	I/O	GPIO port A
K3	VDDIO			Pad power	Digital I/O power, 3.3V
K18	D[14]	1	Low	I/O	Data I/O
K19	A[14]/DRA[13]	1	Low	O	System byte address / SDRAM address
K20	D[15]	1	Low	I/O	Data I/O
L1	TXD[1]	1	High	O	UART 1 transmit data out
L2	LEDDRV	1	Low	O	IR LED drive
L3	PA[3]	1	Input‡	I/O	GPIO port A
L18	VDDIO			Pad power	Digital I/O power, 3.3V
L19	D[16]	1	Low	I/O	Data I/O
L20	A[16]/DRA[11]	1	Low	O	System byte address / SDRAM address
M1	RXD[1]			I	UART 1 receive data input
M2	CTS			I	UART 1 clear to send input
M3	PA[0]	1	Input‡	I/O	GPIO port A
M18	A[15]/DRA[12]	1	Low	O	System byte address / SDRAM address
M19	A[17]/DRA[10]	1	Low	O	System byte address / SDRAM address
M20	nTRST			I	JTAG async reset input
N1	DSR			I	UART 1 data set ready input
N2	nTEST[1]	With p/u*		I	Test mode select input
N3	PHDIN			I	Photodiode input

Table 21. 204-Ball TFBGA Ball Listing (Continued)

Ball Location	Name	Strength†	Reset State	Type	Description
V2	VSSIO			Pad ground	I/O ground
V3	VSSIO			Pad ground	I/O ground
V4	PD[7]/SDQM[1]	1	Low	I/O	GPIO port D / SDRAM byte lane mask
V5	PD[4]	1	Low	I/O	GPIO port D
V6	PD[2]	1	Low	I/O	GPIO port D
V7	SSICLK	1	Input‡	I/O	DAI/CODEC/SSI2 serial clock
V8	SSIRXDA			I/O	DAI/CODEC/SSI2 serial data input
V9	nADCCS	1	High	O	SSI1 ADC chip select
V10	VDDIO			Pad power	Digital I/O power, 3.3V
V11	ADCCLK	1	Low	O	SSI1 ADC serial clock
V12	COL[7]	1	High	O	Keyboard scanner column drive
V13	COL[4]	1	High	O	Keyboard scanner column drive
V14	TCLK			I	JTAG clock
V15	BUZ	1	Low	O	Buzzer drive output
V16	D[29]	1	Low	I/O	Data I/O
V17	A[26]/DRA[1]	2	Low	O	System byte address / SDRAM address
V18	VDDIO			Pad power	Digital I/O power, 3.3 V
V19	VDDIO			Pad power	Digital I/O power, 3.3 V
V20	A[24]/DRA[3]	‘	Low	O	System byte address / SDRAM address
W1	VSSIO			Pad ground	I/O ground
W2	VSSIO			Pad ground	I/O ground
W3	VSSIO			Pad ground	I/O ground
W4	PD[6]/SDQM[0]	1	Low	I/O	GPIO port D / SDRAM byte lane mask
W5	TMS	with p/u*		I	JTAG mode select
W6	PD[1]	1	Low	I/O	GPIO port D
W7	SSITXFR	1	Low	I/O	DAI/CODEC/SSI2 frame sync
W8	SSIRXFR	1	Input‡	I/O	DAI/CODEC/SSI2 frame sync
W9	VSSCORE			Core Ground	Core Ground
W10	DRIVE[1]	2	High / Low	I/O	PWM drive output

Table 21. 204-Ball TFBGA Ball Listing (Continued)

Ball Location	Name	Strength†	Reset State	Type	Description
W11	ADCOUT	1	Low	O	SSI1 ADC serial data output
W12	FB[0]			I	PWM feedback input
W13	COL[5]	1	High	O	Keyboard scanner column drive
W14	COL[2]	1	High	O	Keyboard scanner column drive
W15	COL[0]	1	High	O	Keyboard scanner column drive
W16	D[30]	1	Low	I/O	Data I/O
W17	A[27]/DRA[0]	2	Low	O	System byte address / SDRAM address
W18	D[26]	1	Low	I/O	Data I/O
W19	VDDIO			Pad power	Digital I/O power, 3.3V
W20	D[25]	1	Low	I/O	Data I/O
Y1	VSSIO			Pad ground	I/O ground
Y2	VSSIO			Pad ground	I/O ground
Y3	VSSIO			Pad ground	I/O ground
Y4	PD[5]	1	Low	I/O	GPIO port D
Y5	PD[3]	1	Low	I/O	GPIO port D
Y6	PD[0]/LEDFLSH	1	Low	I/O	GPIO port D / LED blinker output
Y7	SSITXDA	1	Low	O	DAI/CODEC/SSI2 serial data output
Y8	ADCIN			I	SSI1 ADC serial input
Y9	VDDCORE			Core power	Digital core power, 2.5V
Y10	DRIVE[0]	2	Input‡	I/O	PWM drive output
Y11	SMPCLK	1	Low	O	SSI1 ADC sample clock
Y12	FB[1]			I	PWM feedback input
Y13	COL[6]	1	High	O	Keyboard scanner column drive
Y14	COL[3]	1	High	O	Keyboard scanner column drive
Y15	COL[1]	1	High	O	Keyboard scanner column drive
Y16	D[31]	1	Low	I/O	Data I/O
Y17	D[28]	1	Low	I/O	Data I/O
Y18	D[27]	1	Low	I/O	Data I/O
Y19	A[25]/DRA[2]	2	Low	O	System byte address / SDRAM address

Table V. 256-Ball PBGA Ball Listing (Continued)

Ball Location	Name	Type	Description
F7	SDCKE	O	SDRAM clock enable output
F8	DD[3]	O	LCD serial display data
F9	A[1]	O	System byte address
F10	D[6]	I/O	Data I/O
F11	VSSRTC	RTC ground	Real time clock ground
F12	BATOK	I	Battery ok input
F13	nBATCHG	I	Battery changed sense input
F14	VSSIO	Pad ground	I/O ground
F15	D[11]	I/O	Data I/O
F16	VDDIO	Pad power	Digital I/O power, 3.3V
G1	PB[1]	I	GPIO port B
G2	VDDIO	Pad power	Digital I/O power, 3.3V
G3	TDO	O	JTAG data out
G4	PB[4]	I	GPIO port B
G5	PB[6]	I	GPIO port B
G6	VSSRTC	Core ground	Real time clock ground
G7	VSSRTC	RTC ground	Real time clock ground
G8	DD[0]	O	LCD serial display data
G9	D[3]	I/O	Data I/O
G10	VSSRTC	RTC ground	Real time clock ground
G11	A[7]	O	System byte address
G12	A[8]	O	System byte address
G13	A[9]	O	System byte address
G14	VSSIO	Pad ground	I/O ground
G15	D[12]	I/O	Data I/O
G16	D[13]	I/O	Data I/O
H1	PA[7]	I	GPIO port A
H2	PA[5]	I	GPIO port A
H3	VSSIO	Pad ground	I/O ground
H4	PA[4]	I	GPIO port A
H5	PA[6]	I	GPIO port A
H6	PB[0]	I	GPIO port B
H7	PB[2]	I	GPIO port B
H8	VSSRTC	RTC ground	Real time clock ground
H9	VSSRTC	RTC ground	Real time clock ground
H10	A[10]	O	System byte address
H11	A[11]	O	System byte address
H12	A[12]	O	System byte address
H13	A[13]/DRA[14]	O	System byte address / SDRAM address
H14	VSSIO	Pad ground	I/O ground
H15	D[14]	I/O	Data I/O
H16	D[15]	I/O	Data I/O
J1	PA[3]	I	GPIO port A
J2	PA[1]	I	GPIO port A
J3	VSSIO	Pad ground	I/O ground
J4	PA[2]	I	GPIO port A
J5	PA[0]	I	GPIO port A
J6	TXD[1]	O	UART 1 transmit data out

Table V. 256-Ball PBGA Ball Listing (Continued)

Ball Location	Name	Type	Description
J7	CTS	I	UART 1 clear to send input
J8	VSSRTC	RTC ground	Real time clock ground
J9	VSSRTC	RTC ground	Real time clock ground
J10	A[17]/DRA[10]	O	System byte address / SDRAM address
J11	A[16]/DRA[11]	O	System byte address / SDRAM address
J12	A[15]/DRA[12]	O	System byte address / SDRAM address
J13	A[14]/DRA[13]	O	System byte address / SDRAM address
J14	nTRST	I	JTAG async reset input
J15	D[16]	I/O	Data I/O
J16	D[17]	I/O	Data I/O
K1	LEDDRV	O	IR LED drivet
K2	PHDIN	I	Photodiode input
K3	VSSIO	Pad ground	I/O ground
K4	DCD	I	UART 1 data carrier detect
K5	nTEST[1]	I	Test mode select input
K6	EINT[3]	I	External interrupt
K7	VSSRTC	RTC ground	Real time clock ground
K8	ADCIN	I	SSI1 ADC serial input
K9	COL[4]	O	Keyboard scanner column drive
K10	TCLK	I	JTAG clock
K11	D[20]	I/O	Data I/O
K12	D[19]	I/O	Data I/O
K13	D[18]	I/O	Data I/O
K14	VSSIO	Pad ground	I/O ground
K15	VDDIO	Pad power	Digital I/O power, 3.3V
K16	VDDIO	Pad power	Digital I/O power, 3.3V
L1	RXD[1]	I	UART 1 receive data input
L2	DSR	I	UART 1 data set ready input
L3	VDDIO	Pad power	Digital I/O power, 3.3V
L4	nEINT[1]	I	External interrupt input
L5	PE[2]/CLKSEL	I	GPIO port E / clock input mode select
L6	VSSRTC	RTC ground	Real time clock ground
L7	PD[0]/LEDFLSH	I/O	GPIO port D / LED blinker output
L8	VSSRTC	Core ground	Real time clock ground
L9	COL[6]	O	Keyboard scanner column drive
L10	D[31]	I/O	Data I/O
L11	VSSRTC	RTC ground	Real time clock ground
L12	A[22]/DRA[5]	O	System byte address / SDRAM address
L13	A[21]/DRA[6]	O	System byte address / SDRAM address
L14	VSSIO	Pad ground	I/O ground
L15	A[18]/DRA[9]	O	System byte address / SDRAM address
L16	A[19]/DRA[8]	O	System byte address / SDRAM address
M1	nTEST[0]	I	Test mode select input
M2	nEINT[2]	I	External interrupt input
M3	VDDIO	Pad power	Digital I/O power, 3.3V
M4	PE[0]/BOOTSEL[0]	I	GPIO port E / Boot mode select
M5	TMS	I	JTAG mode select
M6	VDDIO	Pad power	Digital I/O power, 3.3V

Table W. JTAG Boundary Scan Signal Ordering (Continued)

LQFP Pin No.	TFBGA Ball	PBGA Ball	Signal	Type	Position
44	T3	N1	nEXTFIQ	I	79
45	R1	L5	PE[2]/CLKSEL	I/O	80
46	R2	N2	PE[1]/BOOTSEL1	I/O	83
47	T1	M4	PE[0]/BOOTSEL0	I/O	86
53	T2	T2	PD[7]/SDQM[1]	I/O	89
54	V4	T3	PD[6/SDQM[0]]	I/O	92
55	W4	N5	PD[5]	I/O	95
56	Y4	R3	PD[4]	I/O	98
59	V5	T4	PD[3]	I/O	101
60	W5	N6	PD[2]	I/O	104
61	Y5	R4	PD[1]	I/O	107
62	V6	L7	PD[0]/LEDFLSH	O	110
68	W6	T6	SSIRXFR	I/O	122
69	Y6	K8	ADCIN	I	125
70	W8	R6	nADCCS	O	126
75	Y8	M8	DRIVE1	I/O	128
76	V9	T8	DRIVE0	I/O	131
77	W10	N8	ADCCLK	O	134
78	Y10	R8	ADCOUT	O	136
79	V11	N9	SMPCLK	O	138
80	W11	T9	FB1	I	140
82	Y11	M9	FB0	I	141
83	Y12	R9	COL7	O	142
84	W12	L9	COL6	O	144
85	V12	T10	COL5	O	146
86	Y13	K9	COL4	O	148
87	W13	R10	COL3	O	150
88	V13	N10	COL2	O	152
91	Y14	R11	COL1	O	154
92	W14	M10	COL0	O	156
93	A1	T12	BUZ	O	158
94	V14	L10	D[31]	I/O	160
95	Y15	R12	D[30]	I/O	163
96	W15	N11	D[29]	I/O	166
97	V15	T13	D[28]	I/O	169
99	Y16	R13	A[27]/DRA[0]	Out	172
100	W16	M11	D[27]	I/O	174
101	V16	T14	A[26]/DRA[1]	O	177

Table W. JTAG Boundary Scan Signal Ordering (Continued)

LQFP Pin No.	TFBGA Ball	PBGA Ball	Signal	Type	Position
102	Y17	N12	D[26]	I/O	179
103	W17	R14	A[25]/DRA[2]	O	182
104	Y18	T15	D[25]	I/O	184
105	V17	N13	HALFWORD	O	187
106	W18	R16	A[24]/DRA[3]	O	189
109	Y19	P15	D[24]	I/O	191
110	W20	M13	A[23]/DRA[4]	O	194
111	U18	N16	D[23]	I/O	196
112	V20	L12	A[22]/DRA[5]	O	199
113	U19	N15	D[22]	I/O	201
114	U20	L13	A[21]/DRA[6]	O	204
115	T19	M16	D[21]	I/O	206
117	T20	M15	A[20]/DRA[7]	O	209
118	R19	K11	D[20]	I/O	211
119	R20	L16	A[19]/DRA[8]	O	214
120	T18	K12	D[19]	I/O	216
121	P19	L15	A[18]/DRA[9]	O	219
122	P20	K13	D[18]	I/O	221
126	R18	J10	A[17]/DRA[10]	O	224
127	N19	J16	D[17]	I/O	226
128	N20	J11	A[16]/DRA[11]	O	229
129	P18	J15	D[16]	I/O	231
130	M19	J12	A[15]/DRA[12]	O	234
131	N18	H16	D[15]	I/O	236
132	L20	J13	A[14]/DRA[13]	O	239
133	L19	H15	D[14]	I/O	241
134	M18	H13	A[13]/DRA[14]	O	244
135	K20	G16	D[13]	I/O	246
136	K19	H12	A[12]	O	249
137	K18	G15	D[12]	I/O	251
138	J20	H11	A[11]	O	254
141	J19	F15	D[11]	I/O	256
142	H20	H10	A[10]	O	259
143	H19	E16	D[10]	I/O	261
144	J18	G13	A[9]	O	264
145	K3	E15	D[9]	I/O	266
146	Y3	G12	A[8]	O	269
147	G20	D16	D[8]	I/O	271

Revision History

Revision	Date	Changes
PP1	NOV 2003	First preliminary release.
F1	AUG 2005	Updated SDRAM timing. Added MSL data.

Contacting Cirrus Logic Support

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